



Product Change Notification

106709 - 02

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Americas Contact: asmo.pcn@intel.com

Asia Pacific Contact: apagccb@intel.com

Europe Email: eccb@intel.com

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Product Change Notification

Change Notification #: 106709 - 02
Change Title: Intel NetStructure(R) MPCMM0002Q Chassis Management Module, PCN 106709-02, Product Design, changes to faceplate, front panel LED, EMI filter, ejector handle, new firmware, changes to faceplate, front panel LED, EMI filter, PCB layout, capacitors 16V and 100V, RJ45 connector, substituted RoHS label, Reason for Revision: Label change, additional details on faceplate changes, Safety Note
Date of Publication: July 27, 2007

Key Characteristics of the Change:
Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Aug 27, 2007
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Description of Change to the Customer:

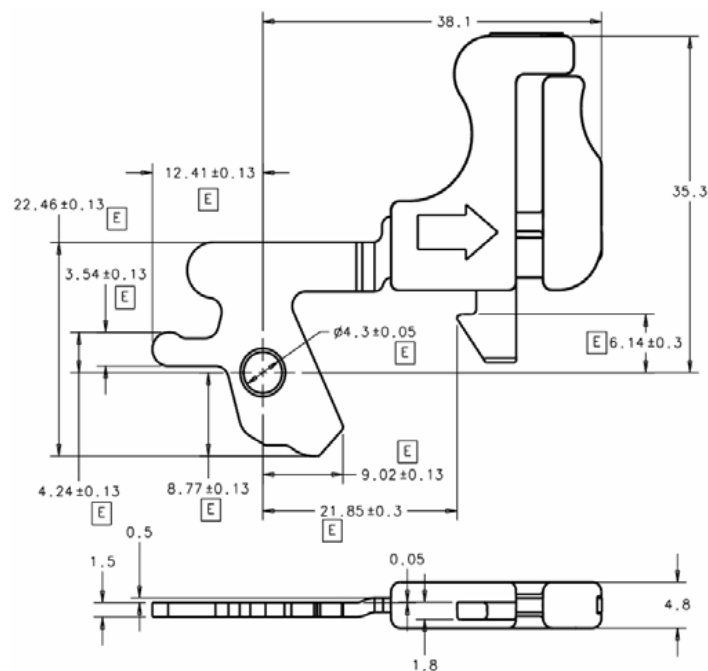
Reason for Revision: Label change, additional details on faceplate changes, Safety Note

1. Following changes were made to the faceplate to accommodate new ejector handle and changes to DSUB15 connector for telecom alarm:
 - a. Added hex slot to DSUB15 connector
 - b. Added chamfer to accommodate new ejector handle
 - c. Changed guide pin to resolve deformation of front panel
 - d. Changed thumb screw size to use standard AdvancedTCA thumb screw.
 - e. Changed faceplate overlay to accommodate new thumb screw and new ejector handle.
 - f. Removed spring washer as not needed for new ejector handle.

2. Front panel LEDs changed from tri-color LED to bi-color LED due to supplier discontinuation of product. The wavelengths of original and new LEDs are as follows:

Dominant Wavelength	Original tri-color LED	New bi-color LED
Green	570nm	570nm
Red	645nm	628nm
Blue	466nm	470nm

3. Removed EMI filter from DSUB15 connector and implemented filter cap.
4. Optimized component locations on board for yield improvements.
5. Changed ejector handle to improve ease of operation and reliability. New ejector handle drawing is shown below.



The below changes were introduced in PCN106709-01:

6. Chassis management firmware version changed from 6.1.0.2779 to 6.1.4.39. Please refer to the following web site for Software Specification Update and other technical documentation: <http://www.intel.com/design/telecom/products/cbp/atca/9634/techdocs.htm>
7. Capacitor 16V changed to extend lifetime in high temperature condition.
8. Capacitor 100V changed to extend lifetime in high temperature condition.
9. RJ45 connector changed to improve manufacturing yield.
10. RoHS regulatory label removed as the logo is printed on PCB.
11. PCB layout changed to accommodate new DSUB15 EMI filter and support tri-color and bi-color LED.

The below changes were introduced in PCN106709-02:

12. Product label changed. New label is shown below.



13. Perchlorate Material Safety Note added inside the packaging box.

Customer Impact of Change and Recommended Action:

1. No impact to customer.
2. No impact to customer.
3. L-COM filter is no longer required when using Telecom Alarm port, as documented in the Technical Specification Update.
4. No impact to customer.
5. Please refer to the Technical Product Specification for operating instructions of the new handle.
6. Please review Software Specification Update document for details on firmware 6.1.4.39.
7. No impact to customer.
8. No impact to customer.
9. No impact to customer.
10. No impact to customer.
11. No impact to customer.
12. No impact to customer.
13. No impact to customer.

Products Affected / Intel Ordering Codes:

Pre Change Product Code	Pre Change MM#	Pre Change TA	Pre Change PBA	Post Change Product Code	Post Change MM#	Post Change TA	Post Change PBA
MPCMM0002Q	875468	D52412-003	D37185-203	MPCMM0002Q	875468	D69470-004	D37185-303

Reference Documents / Attachments:

Document:**Location #:**

Software Specification Update <http://www.intel.com/design/telecom/products/cbp/atca/9634/techdocs.htm>

PCN Revision History:

Date of Revision:**Revision Number:****Reason:**

September 28, 2006

00

Originally Published PCN

May 24, 2007

01

Changed PCB layout, capacitors 16V and 100V, RJ45 connector, Updated FW and substituted RoHS label, deleted color change of jumper J3.

July 24, 2007

02

Label change, additional details on faceplate changes, Safety Note